ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1	IDC Web Site for Information on IDC 1752 Standard					Form Type * Declaration Class *			laterials and	rials and Mfg Information							
Supplier Information																	
Company	Company name*				Company unique ID			Unique ID Authority					Respo	Response Date*			
onsemi														2024-05-03			
Contact Name				Title - Conta	Title - Contact			Phone - Contact*					Emai	Email - Contact*			
Product-I	Env-Steward	ls		Product Envi	Product Enviro Compliance			NA					Prod	Product-Env-Stewards@onsemi.com			
Authorize	Authorized Representative*				Title - Representative			Phone - Representative*				Emai	Email - Representative*				
Product-I	Env-Steware	ls		Product Enviro Compliance				NA				Prod	Product-Env-Stewards@onsemi.com				
	Requester	er Item Number Mfr Item		Number Mfr Item Name			Effective D	Date	Version	1	Manufacturing Site		Weig	ht*	UOM	Unit Type	
	AR01300 A0-DPBI		CSSM00SPC R	00SPC 1.2 MP 1/3 CIS			2024-05-03	3		r.	TA1		264.2	22	mg	Each	
Manufa	Manufacturing Process Information																
	Terminal Plating / Grid Array Material		erminal Base Alloy J-STD-02		J-STD-020 MS	L Rating	Rating Peak Prod		cess Body Temperature Max Time at Peak		Peak Tempe	Temperature Number		nber of Reflow Cycles			
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy 4		4		260			С	30		conds 3				
Comments										·	·			·			
For more	information	regarding material com	position	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	57.0	mg		Misc.	proprietary data		0.2166	mg
			Supplier	Silicon (Si)	7440-21-3		56.2191	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5643	mg
Die Attach	2.5	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9375	mg
			Supplier	Ethylene Glycol	107-21-1		0.025	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.075	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.525	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9375	mg
Imaging Lens	60.5	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.025	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		0.2166 mg 56.2191 mg 0.5643 mg 0.9375 mg 0.025 mg 0.075 mg 0.525 mg 0.9375 mg	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		3.025	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.025	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3025	mg m
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.025	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.025	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		42.0475	mg
Lid Attach	2.6	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.8216	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1352	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.8216	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.8216	mg
Mold Compound-Black	54.0	mg		Phenolic Resin	proprietary data		8.1	mg
			Supplier	Oxirane	39817-09-9		8.1	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.62	mg
			Supplier	Carbon Black (C)	1333-86-4		0.54	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.56	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.08	mg
Substrate and Solder Mask	87.4	mg	Supplier	Acetophenone	98-86-2		1.713	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		19.3941	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1449	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.1537	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2884	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2884	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4261	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.74	mg
			Supplier	Copper (Cu)	7440-50-8	42.389	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.8624	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5	0.22	mg